

REMARKS

Claims 1-7 are all the claims pending in the application. Claim 7 has been amended to make a grammatical change without changing the scope of the claim.

I. Election/Restriction

Applicants note that the Examiner did not specifically respond to Applicants' remarks in the Amendment filed on October 25, 2005 or in the Amendment filed on April 5, 2005, that claim 2 is a linking claim as defined in MPEP § 809.03. Applicants requested that claim 2 be examined with claim 1 in accordance with MPEP § 809.03 and rejoinder of the process claims 2-5, upon allowance of the product claims 1 and 6-7 and/or linking claim 2. See also MPEP § 821.04 regarding rejoinder of method claims.

However, Applicants note that claim 2 is indicated as being rejected in the body of the Action and the Examiner indicated by telephone that claim 2 was in fact examined and included among the rejected claims in the Action dated April 25, 2006. A Statement of Substance of Interview is being filed herewith; however, Applicants respectfully request confirmation and clarification of this matter from the Examiner for the record. Applicants further request rejoinder of the process claims, upon allowance of the product claims 1 and 6-7 and/or linking claim 2.

II. Response to Objection to the Specification

The Examiner has objected to the title of the invention as not being descriptive, stating that a new title clearly indicative of the invention to which the claim is directed is required.

Applicants have amended the title as agreed to by the Examiner in the present application to obviate the objection. Accordingly, Applicants respectfully request withdrawal of the objection to the specification.

III. Response to Rejection under 35 U.S.C. § 102

Claims 1, 2 and 6 are rejected under 35 U.S.C. § 102(b) as being anticipated by Igarashi et al (U.S. Patent No. 5,990,546).

Applicants respectfully traverse the rejection and submit that Igarashi et al does not disclose, teach or suggest all elements of the present claims. Specifically, Igarashi et al does not disclose, teach or suggest a thermosetting sheet having tackiness as recited in present claim 1. Therefore, Igarashi et al does not disclose, teach or suggest at least two characteristics of the present invention.

It appears that there is a misunderstanding as to the difference between a "bonding agent" and a "bonding sheet".

As pointed out in the arguments presented in the Amendment filed on October 25, 2005 and the Response filed on April 5, 2006, Igarashi et al does not disclose, teach or suggest a "thermosetting sheet material" as recited in present claim 1. Specifically, as indicated in the Response filed April 5, 2006, the term "thermosetting" is used only at lines 27-28 of column 5 of Igarashi et al in the context of "a thermoplastic or thermosetting bonding agent". Thus, a sheet having a thermosetting property is not disclosed, taught or suggested by Igarashi et al.

Moreover, Igarashi et al teaches that the semiconductor chip is sealed by a bonding sheet using an epoxy-rubber resin as a bonding agent. The use of the epoxy-rubber resin as a bonding agent suggests to one of ordinary skill in the art that the bonding sheet itself does not have tackiness. Further, there is no description in Igarashi et al which teaches or suggests that the bonding sheet itself has tackiness. Thus, Igarashi et al does not disclose, teach or suggest a thermosetting sheet material having tackiness.

The present invention is characterized in that a thermosetting sheet material having tackiness is used. A sheet which does not have thermosetting properties cannot be used in the intended application (the field in which appropriate level of thermosetting property is required). Moreover, a mere thermosetting sheet having no tackiness does not exert the effects of the present invention. Therefore, claim 1 is not anticipated nor rendered obvious by the art of record.

Claim 2 includes the same distinguishing recitations as claim 1 and 6 depends from claim 1 and is distinguished over the art for at least the same reasons as claim 1. Further, Igarashi et al does not specifically disclose a rubber-containing or rubber-modified polycarbodiimide resin and therefore claim 6 is not anticipated nor rendered obvious by the art of record.

Accordingly, Applicants respectfully request withdrawal of the §102 rejection.

IV. Response to Claim Rejections Under 35 U.S.C. § 103

Claim 7 is rejected under 35 U.S.C. § 103(a) as allegedly being unpatentable over Igarashi et al.

The Examiner recognizes that Igarashi et al does not explicitly disclose the tackiness of the sheet material as recited in the claim. However it is the Examiner's position that tackiness is a result effective variable and it would have been obvious for one of ordinary skill in the art to adjust the tackiness of the sheet material in terms of ball tack in accordance with the process for forming the sheet material, for the purpose of handling the package during or after the packaging process or testing the chip in the package.

Applicants respectfully traverse the rejection and submit that Igarashi et al does not disclose, teach or suggest a thermosetting sheet material having tackiness as recited in present claim 1 from which claim 7 depends. Therefore, for at least this reason claim 7 is distinguished over the art of record.

Additionally, since Igarashi et al does not teach or suggest a thermosetting sheet material having tackiness, there is no motivation for one of ordinary skill in the art to modify the disclosure of Igarashi et al to arrive at the tackiness of the sheet material before thermosetting of 2 to 15 in terms of ball tack as recited in present claim 7. For this additional reason, claim 7 is distinguished over the art of record.

Accordingly, Applicants respectfully request withdrawal of the §103 rejection.

V. Conclusion

In view of the above, reconsideration and allowance of this application are now believed to be in order, and such actions are hereby solicited. If any points remain in issue which the Examiner feels may be best resolved through a personal or telephone interview, the Examiner is kindly requested to contact the undersigned at the telephone number listed below.

The USPTO is directed and authorized to charge all required fees, except for the Issue Fee and the Publication Fee, to Deposit Account No. 19-4880. Please also credit any overpayments to said Deposit Account.

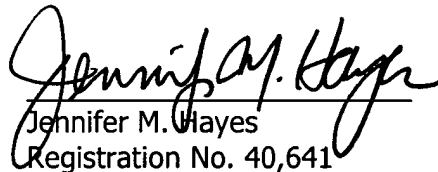
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